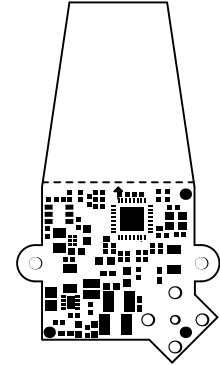
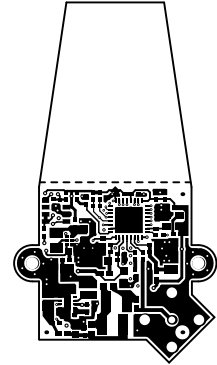


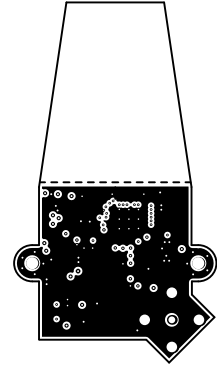
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/18/2018 12:03:35 PM	TEXAS INSTRUMENTS	



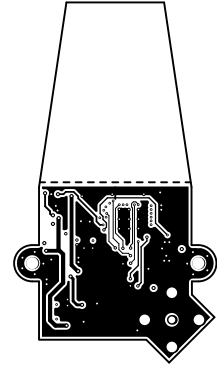
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/18/2018 12:03:36 PM	TEXAS INSTRUMENTS	



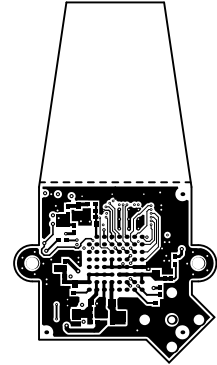
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/18/2018 12:03:37 PM	TEXAS INSTRUMENTS	



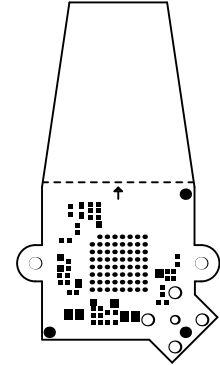
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = Signal Layer 1	GENERATED : 1/18/2018 12:03:38 PM	TEXAS INSTRUMENTS	



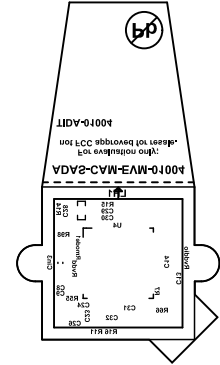
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = Signal Layer 2	GENERATED : 1/18/2018 12:03:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/18/2018 12:03:40 PM	TEXAS INSTRUMENTS	

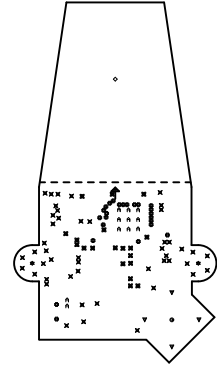


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/18/2018 12:03:41 PM	TEXAS INSTRUMENTS	



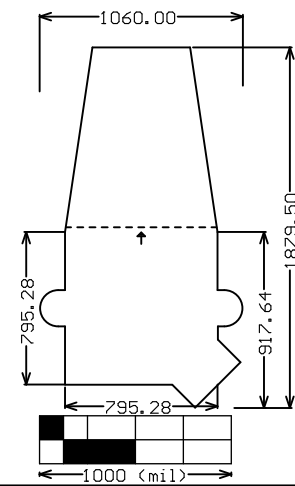
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 1/18/2018 12:03:42 PM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type
*	2	62.99mil (1.600mm)	NPTH	Round
◇	1	280.00mil (7.112mm)	NPTH	Round
⊠	24	6.00mil (0.152mm)	PTH	Round
⌘	11	7.87mil (0.200mm)	PTH	Round
⊠	19	8.00mil (0.203mm)	PTH	Round
⊠	47	10.00mil (0.254mm)	PTH	Round
○	1	35.43mil (0.900mm)	PTH	Round
▽	4	55.12mil (1.400mm)	PTH	Round
	109 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/18/2018 12:03:43 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01004	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/18/2018 12:03:44 PM	TEXAS INSTRUMENTS	

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